

To: Technology Center: 2800 Total Pages Sent: 3
 Facsimile Number: (571) 273-8300

From: Yingsheng Tung
 Texas Instruments Incorporated
 Facsimile: 972-917-4418
 Phone: 972-917-5355

RECEIVED
 CENTRAL FAX CENTER
 NOV 06 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of
Shih-Fang Chuang

Docket Number: TI-36243

Serial No.: **10/717,731**

Art Unit: **2814**

Filed: **11/20/2003**

Examiner: **Hoai V. Pham**

For: **LOW COEFFICIENT OF THERMAL EXPANSION (CTE)
 SEMICONDUCTOR PACKAGING MATERIALS**

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at (571) 273-8300 on the date shown below:

Jackie McBride
 Jackie McBride

11-6-2006
 Date

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET <input type="checkbox"/> NEW APPLICATION <input type="checkbox"/> DECLARATION (# Pages) <input type="checkbox"/> ASSIGNMENT (# Pages) <input type="checkbox"/> FORMAL DRAWINGS <input type="checkbox"/> INFORMAL DRAWINGS <input type="checkbox"/> CONTINUATION APP'N (# Pages)		<input checked="" type="checkbox"/> <u>RESPONSE TO NON-COMPLIANCE WITH CORRECTLY IDENTIFIED CLAIMS</u>	
<small>NAME OF INVENTOR(S):</small> SHIH-FANG CHUANG		<small>RECEIPT DATE & SERIAL NO.:</small> Serial No.: 10/717,731 Conf. No: 8713	
<small>TITLE OF INVENTION:</small> LOW COEFFICIENT OF THERMAL...	<small>TI FILE NO.: DEPOSIT ACCT. NO.:</small> TI-36243 20-0668		
<small>FAXED:</small> 11/06/2006 <small>DUE:</small> 11/30/2006 <small>ATTY/SECY:</small> YT/jsm			

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated
 PO Box 655474, M/S 3998
 Dallas, TX 75265